

<b>STN</b>	<b>Polovodičové súčiastky</b> <b>Mechanické a klimatické skúšobné metódy</b> <b>Časť 26: Skúšanie citlivosti na elektrostatický</b> <b>výboj (ESD)</b> <b>Model ľudského tela (HBM)</b>	<b>STN</b> <b>EN IEC 60749-26</b>  35 8799
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Semiconductor devices - Mechanical and climatic test methods - Part 26: Electrostatic discharge (ESD) sensitivity testing - Human body model (HBM)

Táto norma obsahuje anglickú verziu európskej normy.  
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 01/19

Obsahuje: EN IEC 60749-26:2018, IEC 60749-26:2018

Oznámením tejto normy sa od 19.02.2021 ruší  
STN EN 60749-26 (35 8799) z februára 2015

**127816**

EUROPEAN STANDARD

**EN IEC 60749-26**

NORME EUROPÉENNE

EUROPÄISCHE NORM

March 2018

ICS 31.080.01

Supersedes EN 60749-26:2014

English Version

**Semiconductor devices - Mechanical and climatic test methods -  
Part 26: Electrostatic discharge (ESD) sensitivity testing -  
Human body model (HBM)  
(IEC 60749-26:2018)**

Dispositifs à semiconducteurs - Méthodes d'essais  
mécaniques et climatiques - Partie 26: Essai de sensibilité  
aux décharges électrostatiques (DES) - Modèle du corps  
humain (HBM)  
(IEC 60749-26:2018)

Halbleiterbauelemente - Mechanische und klimatische  
Prüfverfahren - Teil 26: Prüfung der Empfindlichkeit gegen  
elektrostatische Entladungen (ESD) - Human Body Model  
(HBM)  
(IEC 60749-26:2018)

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**EN IEC 60749-26:2018 (E)****European foreword**

The text of document 47/2438/FDIS, future edition 4 of IEC 60749-26, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 60749-26:2018.

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IEC 60749 (series)	NOTE	Harmonized as EN 60749 (series).
IEC 60749-27	NOTE	Harmonized as EN 60749-27.



IEC 60749-26

Edition 4.0 2018-01

# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



**Semiconductor devices – Mechanical and climatic test methods –  
Part 26: Electrostatic discharge (ESD) sensitivity testing – Human body model  
(HBM)**

**Dispositifs à semiconducteurs – Méthodes d'essais mécaniques et climatiques –  
Partie 26: Essai de sensibilité aux décharges électrostatiques (DES) – Modèle du  
corps humain (HBM)**

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IEC 60749-26

Edition 4.0 2018-01

# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



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**Semiconductor devices – Mechanical and climatic test methods –  
Part 26: Electrostatic discharge (ESD) sensitivity testing – Human body model  
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Partie 26: Essai de sensibilité aux décharges électrostatiques (DES) – Modèle du  
corps humain (HBM)**

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ICS 31.080.01

ISBN 978-2-8322-5256-7

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## CONTENTS

FOREWORD.....	5
1 Scope.....	7
2 Normative references .....	7
3 Terms and definitions .....	7
4 Apparatus and required equipment.....	10
4.1 Waveform verification equipment .....	10
4.2 Oscilloscope .....	11
4.3 Additional requirements for digital oscilloscopes .....	11
4.4 Current transducer (inductive current probe).....	11
4.5 Evaluation loads .....	11
4.6 Human body model simulator .....	12
4.7 HBM test equipment parasitic properties .....	12
5 Stress test equipment qualification and routine verification .....	12
5.1 Overview of required HBM tester evaluations .....	12
5.2 Measurement procedures.....	13
5.2.1 Reference pin pair determination .....	13
5.2.2 Waveform capture with current probe .....	13
5.2.3 Determination of waveform parameters.....	14
5.2.4 High voltage discharge path test.....	17
5.3 HBM tester qualification .....	17
5.3.1 HBM ESD tester qualification requirements .....	17
5.3.2 HBM tester qualification procedure .....	17
5.4 Test fixture board qualification for socketed testers .....	18
5.5 Routine waveform check requirements.....	19
5.5.1 Standard routine waveform check description .....	19
5.5.2 Waveform check frequency.....	19
5.5.3 Alternate routine waveform capture procedure .....	20
5.6 High voltage discharge path check.....	20
5.6.1 Relay testers .....	20
5.6.2 Non-relay testers .....	20
5.7 Tester waveform records.....	20
5.7.1 Tester and test fixture board qualification records.....	20
5.7.2 Periodic waveform check records .....	20
5.8 Safety .....	21
5.8.1 Initial set-up.....	21
5.8.2 Training .....	21
5.8.3 Personnel safety.....	21
6 Classification procedure .....	21
6.1 Devices for classification .....	21
6.2 Parametric and functional testing .....	21
6.3 Device stressing .....	21
6.4 Pin categorization .....	22
6.4.1 General .....	22
6.4.2 No connect pins.....	22
6.4.3 Supply pins.....	23
6.4.4 Non-supply pins.....	23

6.5	Pin groupings.....	24
6.5.1	Supply pin groups.....	24
6.5.2	Shorted non-supply pin groups.....	24
6.6	Pin stress combinations.....	24
6.6.1	Pin stress combination categorization.....	24
6.6.2	Non-supply and supply to supply combinations (1, 2, ... N).....	26
6.6.3	Non-supply to non-supply combinations.....	27
6.7	HBM stressing with a low-parasitic simulator.....	28
6.7.1	Low-parasitic HBM simulator.....	28
6.7.2	Requirements for low parasitics.....	28
6.8	Testing after stressing.....	28
7	Failure criteria.....	28
8	Component classification.....	28
	Annex A (informative) HBM test method flow chart.....	30
	Annex B (informative) HBM test equipment parasitic properties.....	33
B.1	Optional trailing pulse detection equipment / apparatus.....	33
B.2	Optional pre-pulse voltage rise test equipment.....	34
B.3	Open-relay tester capacitance parasitics.....	36
B.4	Test to determine if an HBM simulator is a low-parasitic simulator.....	36
	Annex C (informative) Example of testing a product using Table 2, Table 3, or Table 2 with a two-pin HBM tester.....	38
C.1	General.....	38
C.2	Procedure A (following Table 2):.....	39
C.3	Alternative procedure B (following Table 3):.....	40
C.4	Alternative procedure C (following Table 2):.....	41
	Annex D (informative) Examples of coupled non-supply pin pairs.....	43
	Annex E (normative) Cloned non-supply (I/O) pin sampling test method.....	44
E.1	Purpose and overview.....	44
E.2	Pin sampling overview and statistical details.....	44
E.3	IC product selections.....	45
E.4	Randomly selecting and testing cloned I/O pins.....	46
E.5	Determining if sampling can be used with the supplied Excel spreadsheet.....	46
E.5.1	Using the supplied Excel spreadsheet.....	46
E.5.2	Without using the Excel spreadsheet.....	46
E.6	HBM testing with a sample of cloned I/O pins.....	46
E.7	Examples of testing with sampled cloned I/Os.....	47
	Bibliography.....	50
	Figure 1 – Simplified HBM simulator circuit with loads.....	12
	Figure 2 – Current waveform through shorting wires.....	15
	Figure 3 – Current waveform through a 500 Ω resistor.....	16
	Figure 4 – Peak current short circuit ringing waveform.....	17
	Figure A.1 – HBM test method flow chart (1 of 3).....	30
	Figure B.1 – Diagram of trailing pulse measurement setup.....	33
	Figure B.2 – Positive stress at 4 000 V.....	34
	Figure B.3 – Negative stress at 4 000 V.....	34



Figure B.4 – Illustration of measuring voltage before HBM pulse with a Zener diode or a device .....	35
Figure B.5 – Example of voltage rise before the HBM current pulse across a 9,4 V Zener diode .....	35
Figure B.6 – Diagram of a 10-pin shorting test device showing current probe.....	37
Figure C.1 – Example to demonstrate the idea of the partitioned test.....	38
Figure E.1 – SPL, V1, VM, and z with the Bell shape distribution pin failure curve .....	45
Figure E.2 – I/O sampling test method flow chart .....	49
Table 1 – Waveform specification .....	19
Table 2 – Preferred pin combinations sets .....	25
Table 3 – Alternative pin combinations sets .....	26
Table 4 – HBM ESD component classification levels.....	29
Table C.1 – Product testing in accordance with Table 2 .....	40
Table C.2 – Product testing in accordance with Table 3 .....	41
Table C.3 – Alternative product testing in accordance with Table 2.....	42

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –  
MECHANICAL AND CLIMATIC TEST METHODS –****Part 26: Electrostatic discharge (ESD) sensitivity testing –  
Human body model (HBM)**

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This edition includes the following significant technical changes with respect to the previous edition:

- a) a new subclause relating to HBM stressing with a low parasitic simulator is added, together with a test to determine if an HBM simulator is a low parasitic simulator;

- b) a new subclause is added for cloned non-supply pins and a new annex is added for testing cloned non-supply pins.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
47/2438/FDIS	47/2454/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

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## **SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –**

### **Part 26: Electrostatic discharge (ESD) sensitivity testing – Human body model (HBM)**

#### **1 Scope**

This part of IEC 60749 establishes the procedure for testing, evaluating, and classifying components and microcircuits according to their susceptibility (sensitivity) to damage or degradation by exposure to a defined human body model (HBM) electrostatic discharge (ESD).

The purpose of this document is to establish a test method that will replicate HBM failures and provide reliable, repeatable HBM ESD test results from tester to tester, regardless of component type. Repeatable data will allow accurate classifications and comparisons of HBM ESD sensitivity levels.

ESD testing of semiconductor devices is selected from this test method, the machine model (MM) test method (see IEC 60749-27) or other ESD test methods in the IEC 60749 series. Unless otherwise specified, this test method is the one selected.

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